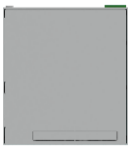
Product

KiWiBot Series x86 Platform

Features:

- Intel® 12/13th Gen Core i3/i5/i7 -U/P/H, Support max 45W
- 1*GbE,2*10GbE RJ45
- 4*USB 5Gbps Type-A，3*USB 2.0 wafer
- 4*RS232/RS485，8*GPIO
- Wi-Fi、BT、4G/5G
- Active Heat Dissipation
- 12~28V DC



Remote Management

Condition Monitoring

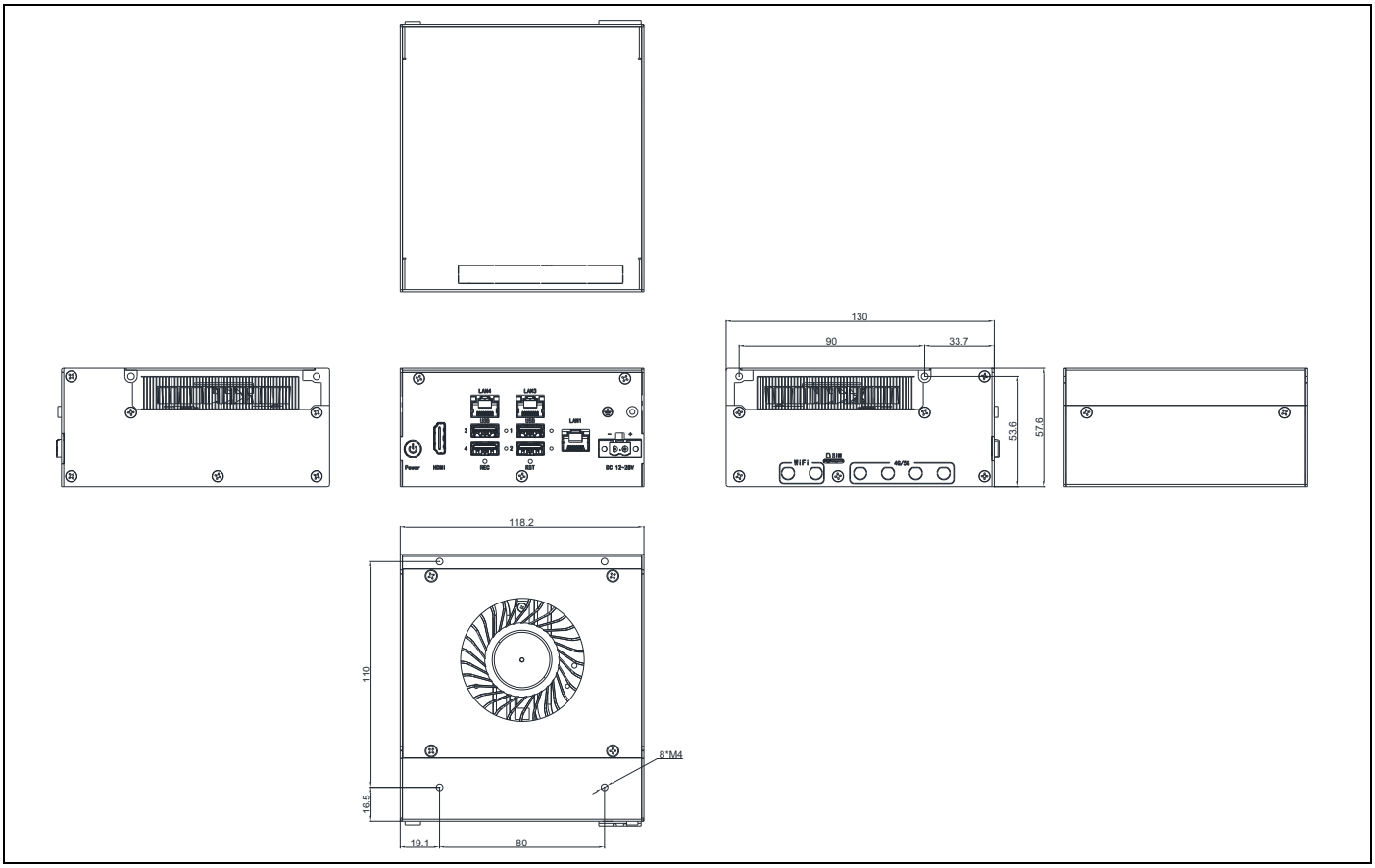
Remote Operation And Maintenance

Safety Control

Product Specification

Model		TER30X-B3
Core Modules	CPU	Support Intel® 12/13th Gen Core i3/i5/i7 -U/P/H, Support max 45W
Memory	Socket	1 * Non-ECC SO-DIMM Slot, Up to DDR5 5200 MT/s
	Max Capacity	Max. 32GB
Graphics	Controller	Intel® Iris® Xe Graphics
Ethernet	Wired Module	1 * Intel® i219-V (10/100/1000 Mbps)
		1 * Intel® i226-V (10/100/1000/2500 Mbps)
		1 * Intel® X710-AT2 (100/1000/2500/10000 Mbps)
Storage	M.2	1 * M.2 Key-M Slot (NVMe SSD, 2280)
Expansion Slots	M.2	1 * M.2 Key-B Slot (USB 5Gbps + USB 2.0, 3052, with 1 * Nano SIM Card Slot)
		1 * M.2 Key-E Slot (PCIe x1 + USB 2.0)
Front I/O	Ethernet	2 * 10GbE (RJ45)
		1 * GbE (RJ45)
	USB	4 * USB 5Gbps (Type-A)
	Display	1 * HDMI: Resolution up to 4096*2304@30Hz (Type-A)
	Button	1 * Power Button + Power LED
		1 * System Reset button
		1 * System Recover button
	Power Input	1 * Power Input (2P, P=5.00/5.08, Terminal Block)
Side I/O	SIM	1 * Nano SIM Card Slots
Internal I/O	Front Panel	1 * Front Panel (Power + Reset + Recovery, wafer)
	Ethernet	1 * GbE (wafer)
	FAN	1 * System Fan (wafer)
	GPIO	8bit GPIO (OS Configurable DI/DO and H/L, wafer)
	Serial	4 * RS232/485 (Jumper Switch, wafer)
	Audio	1 * Audio (Line_Out + Mic) (wafer)
	USB	3 * USB 2.0 (wafer)
Power Supply	Type	AT/ATX
	Power Input Voltage	12 ~ 28V DC
	Connector	1 * Power Input Connector (2P, P=5.08mm, Terminal Block)
	RTC Battery	CR2032 Coin Cell
OS Support	Linux	Ubuntu22.04
Mechanical	Enclosure Material	Aluminum alloy
	Dimensions	118.2mm(L) * 130mm(W) * 57.6mm(H)
	Mounting	Bracket Mounting
Environment	Heat Dissipation System	Active Fan Cooling
	Operating Temperature	-20~50°C (Industrial SSD)
	Storage Temperature	-40~80°C (Industrial SSD)
	Relative Humidity	10 to 95% RH (non-condensing)
	Vibration During Operation	3Grms@5~500Hz, random, 1hr/axis
	Shock During Operation	15G, half sine, 11ms, ±X/Y/Z, 3 shocks/axis

Product Size



I/O